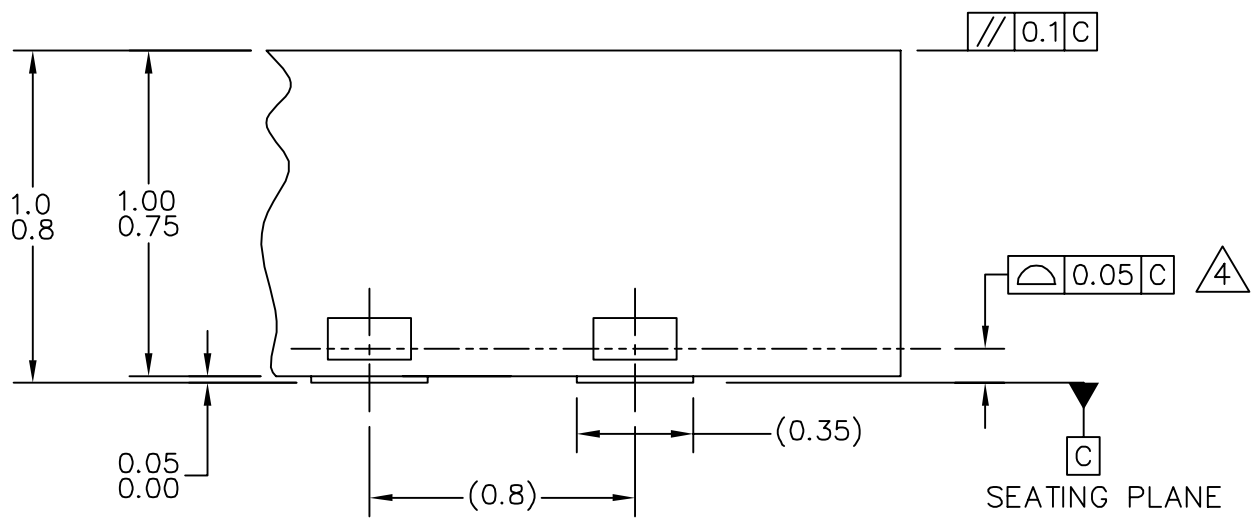
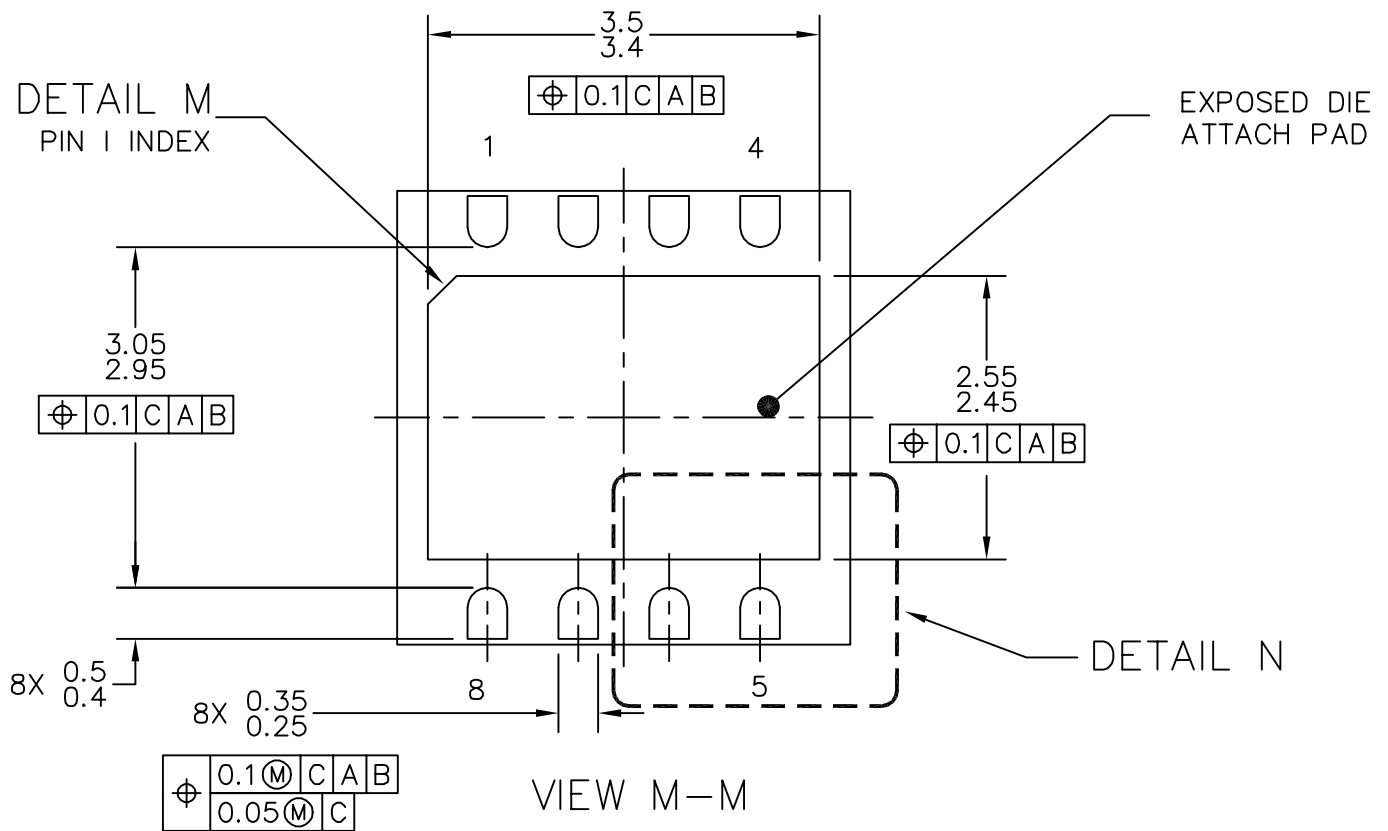
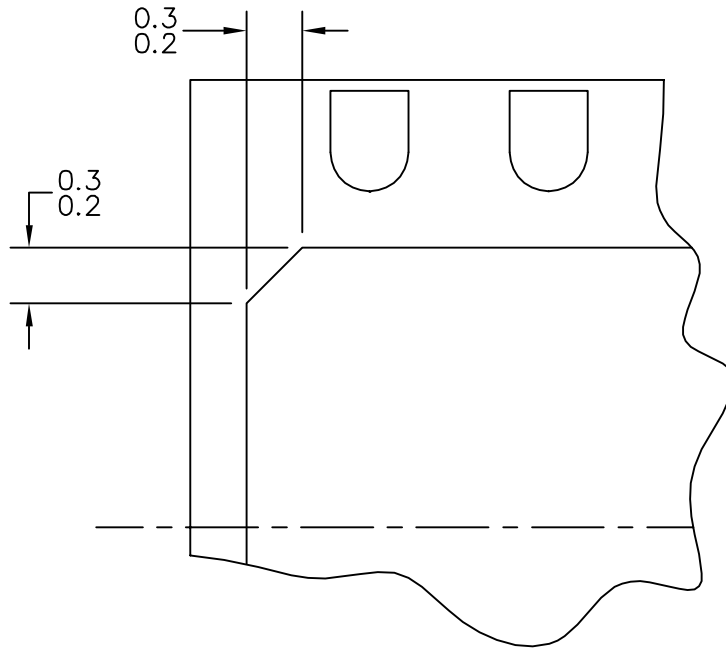


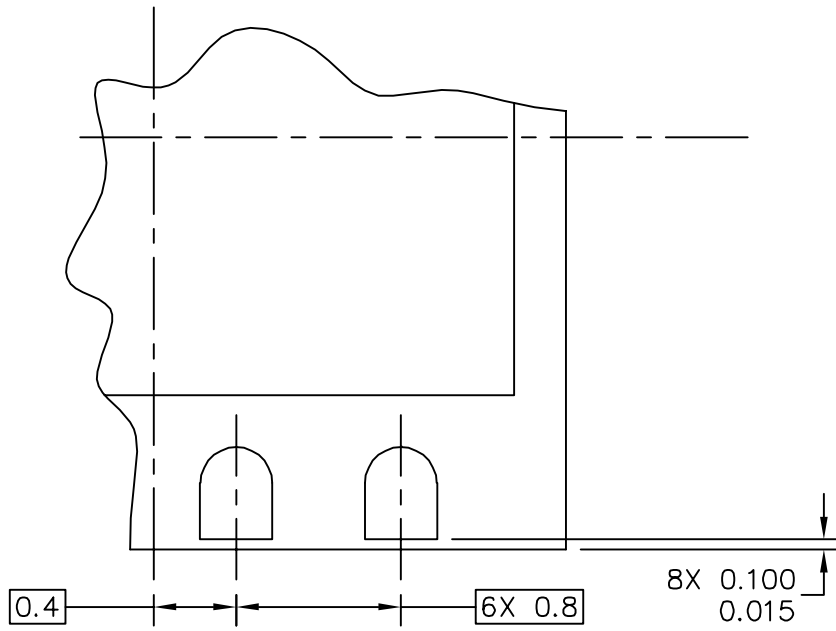
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TITLE: THERMALLY ENHANCED DUAL FLAT NO LEAD PACKAGE (DFN) 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARL10557D	REV: B	
	CASE NUMBER: 1452-02	28 DEC 2005	
	STANDARD: NON-JEDEC		



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TITLE: THERMALLY ENHANCED DUAL FLAT NO LEAD PACKAGE (DFN) 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARL10557D	REV: B	
	CASE NUMBER: 1452-02	28 DEC 2005	
	STANDARD: NON-JEDEC		




DETAIL M
BACKSIDE PIN 1 INDEX



DETAIL N

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TITLE: THERMALLY ENHANCED DUAL FLAT NO LEAD PACKAGE (DFN) 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)	DOCUMENT NO: 98ARL10557D	REV: B	
	CASE NUMBER: 1452-02	28 DEC 2005	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HP-VDFDP-N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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